

Title (en)

AN UNDERCOATING LAYER FORMULATION FOR NON-PLATABLE GRADE SUBSTRATE FOR ELECTROLESS METAL PLATING

Title (de)

UNTERSCHICHTFORMULIERUNG FÜR NICHTPLATTIERBARES SUBSTRAT FÜR STROMLOSE METALLISIERUNG

Title (fr)

FORMULATION DE COUCHE DE SOUS-REVÊTEMENT POUR SUBSTRAT DE QUALITÉ NON GALVANISABLE POUR REVÊTEMENT MÉTALLIQUE ANÉLECTROLYTIQUE

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Application

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Abstract (en)

[origin: WO2008123767A2] Described herein is a coating formulation for non-platable grade substrate prior to undergoing an electroless metal plating process. Said coating formulation comprises of a mixture of multifunctional based monomer and diphenylmethane- 4, 4-diisocyanate (MDI), said multifunctional based monomer has allyl group or alkyl group or vinyl group or ether group or ester group or methacrylate group or acrylate group or phthalate group or combination thereof but does not include multifunctional monomer having hydroxyl group. According to the present invention, the ratio of said multifunctional based monomer is less than or equal (<) to diphenylmethane-4, 4-diisocyanate (MDI). Said coating formulation is mixed in a vacuum chamber for about 30 minutes before being applied to the surface of a non-platable grade substrate.

IPC 8 full level

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